

Tacky Thermosetting Adhesive Tapes

Arlon Innovations Tacky Thermosetting Adhesive Tapes are tacky at room temperature, providing initial bond like a Pressure Sensitive Adhesive (PSA) tape. When heat and pressure are applied, the polymer chains cross-link producing an infusible and insoluble polymer network, which allows the tape to achieve full cure and high bond strength.



**BREAKTHROUGH
SOLUTIONS
THAT STICK**



**A THERMOSET
THAT ACTS
LIKE A PSA**



FEATURE APPLICATIONS

- Transportation
- Automotive
- Airlines
- Trains
- Decorative Cap Sheets
- Home Remodeling
- Thermoforming

BENEFITS OF THERMOSETTING ADHESIVE TAPES OVER PSA TAPES

- Performance in moist environments
- Extreme high adhesion strength
- Resistance to shock, vibration & fatigue
- Thermal, chemical & corrosion resistance
- Dimensional stability & long-term durability

BENEFITS OF THERMOSETTING ADHESIVE TAPES OVER LIQUID ADHESIVES

- Controlled, uniform bond line
- Precise placement
- Pick & place instead of dispensing
- Improved stress distribution
- Ability to bond dissimilar & similar materials
- Minimal clean-up

WHY CHOOSE ARLON INNOVATIONS?

- Leading adhesive manufacturer since 1985
- Ability to custom design for application
- Formulations for many service conditions
- High-quality standards tested in R & D lab
- Large variety of functional substrates
- Partnership with UL certified lab

ARLON INNOVATIONS 5105 TACKY THERMOSET



Arlon Innovations 5105 Tacky Thermoset performs like a Pressure Sensitive Adhesive (PSA) tape at room temperature and cures to a very high strength with heat and pressure. It is B-stage curable to a permanent thermosetting bond. This tape is ideal for bonding parts without the need for clamping or the mess associated with liquid adhesives.

ARLON INNOVATIONS 5202 TACKY THERMOSET



Arlon Innovations 5202 Tacky Thermoset has excellent initial tack and peel strength at room temperature – outperforming most Pressure Sensitive Adhesive (PSA) tapes. With added heat and pressure, the adhesive then cures to an even higher bond strength. It is ideally suited for thermoforming applications of dissimilar and low surface energy substrates.